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IN THE CLAIMS

1 (Previously Presented). A method comprising:
attaching ligands along a polymer bristle to form a semiconductor wafer cleaning
brush.

2 (Original). The method of claim 1 including attaching ligands using a hydrolysis
reaction.

3 (Previously Presented). The method of claim 1 including attaching ligands along a
polyvinyl alcohol polymer.

4 (Previously Presented). The method of claim 1 including using a coupling agent to
attach ligands along a polymer chain.

5 (Original). The method of claim 1 including attaching ligands to provide a
hydrophilic property.

6 (Original). The method of claim 1 including attaching ligands to provide hydrophobic
property.

7 (Original). The method of claim 1 including attaching ligands to provide a reducing
agent property.

8 (Original). The method of claim 1 including attaching ligands to provide an oxidizing
property.

9 (Original). The method of claim 1 including attaching ligands to provide an attraction
to a specific material.

10 (Original). The method of claim 1 including attaching ligands to change the zeta potential.

11 (Original). The method of claim 1 including attaching a ligand having a subchain to the polymer.

12 (Original). The method of claim 11 including attaching a moiety to said subchain to provide a desired property to said ligand.

13 (Previously Presented). A method comprising:

cleaning a semiconductor wafer using a polymer brush having ligands attached along a polymer.

14 (Original). The method of claim 13 including using a brush having ligands attached to polyvinyl alcohol polymer bristles.

15 (Original). The method of claim 13 including using a brush having ligands that to provide a hydrophilic property.

16 (Original). The method of claim 13 including using a brush having ligands that provide a hydrophobic property.

17 (Original). The method of claim 13 including using a brush having ligands that provide a reducing agent property.

18 (Original). The method of claim 13 including using a brush having ligands that provide an oxidizing property.

19 (Original). The method of claim 13 including using a brush having ligands that are attracted to a specific material.

20 (Original). The method of claim 13 including using a brush having ligands having a positive zeta potential.

21 (Original). The method of claim 13 including using a brush having ligands having a negative zeta potential.

22 (Original). The method of claim 13 including using a brush having a ligand having a subchain of at least two carbon atoms.

23 (Previously Presented). The method of claim 22 including using a brush having a moiety on said subchain to provide a property to said ligand.

Claims 24-34 (Canceled).